## Silicon Switching Diode

1N4607

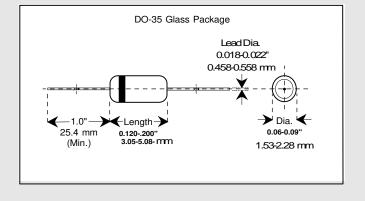
# **DO-35 Glass Package**

# Applications

Used in general purpose applications, where a controlled forward characteristic and fast switching speed are important.

# Features

- Six sigma quality
- Metallurgically bonded
- BKC's Sigma Bond<sup>™</sup> plating for problem free solderability



Maximum Ratings			Symbol	Value	Unit
Peak Inverse Voltage			PIV	85 (Min).	Volts
Average Rectified Current			lavg	200	mAmps
Continuous Forward Current			I <sub>Fdc</sub>	200	mAmps
Peak Surge Current (t <sub>peak</sub> = 1 sec.)			l peak	1.0	Amp
BKC Power Dissipation $T_{L}=50 \text{ °C}, L = 3/8"$ from body			P <sub>tot</sub>	500	mWatts
Operating Temperature Range			T <sub>Op</sub>	-65 to +200	° C
Storage Temperature Range			T <sub>st</sub>	-65 to +200	° C
Electrical Characteristics @ 25 °C*	Symbol			Maximum	Unit
Forward Voltage Drop @ I <sub>F</sub> = 400 mA	$V_{\rm F}$	***		1.10	Volts
Breakdown Voltage @ Ι <sub>R</sub> = 25 μA	PIV	85			Volts
Reverse Leakage Current @ $V_{R} = 50 V$	I <sub>R</sub>			100	μΑ
Reverse Recovery time (note 1)	t <sub>rr</sub>			10	nSecs

Note 1: Per Method 4031-A with I<sub>F</sub> = 10 mA, Vr = 6 V, R<sub>I</sub> = 100 Ohms. \* UNLESS OTHERWISE SPECIFIED



## Silicon Switching Diode

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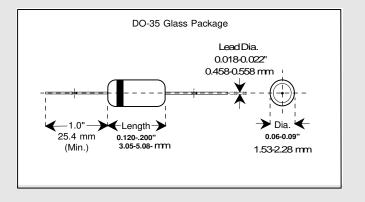
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Continuous Forward Current			I <sub>Fdc</sub>	500	mAmps
Peak Surge Current (t <sub>peak</sub> = 1 sec.)			I <sub>peak</sub>	1.0	Amp
BKC Power Dissipation $T_L = 50 \text{ °C}, L = 3/8"$ from body			P <sub>tot</sub>	500	mWatts
Operating Temperature Range			T <sub>Op</sub>	-65 to +150	° C
Storage Temperature Range			T <sub>st</sub>	-65 to +150	° C
Electrical Characteristics @ 25 °C*	Symbol	Mi	nimum	Maximum	Unit
Forward Voltage Drop @ $I_F = 400 \text{ mA}$	$V_{F}$	*	**	1.10	Volts
Breakdown Voltage @ Ι <sub>R</sub> = 25 μA	PIV	;	85		Volts
Reverse Leakage Current @ V <sub>R</sub> = 50 V	I <sub>R</sub>			100	μΑ
Reverse Recovery time (note 1)	t <sub>rr</sub>			10	nSecs

Note 1: Per Method 4031-A with  $I_F = 10 \text{ mA}$ , Vr = 6 V,  $R_I = 100 \text{ Ohms}$ . \* UNLESS OTHERWISE SPECIFIED



# Silicon Switching Diode



L-35 Glass Package

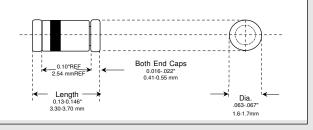
# **Applications**

Used in general purpose applications, where a controlled forward characteristic and fast switching speed are important.

# **Features**

- Six sigma quality
- Metallurgically bonded
- BKC's Sigma Bond<sup>™</sup> plating for problem free solderability

#### LL-34/35 MINI MELF Surface Mount Package DO-213AA



Maximum Ratings			Symbol	Value	Unit
Peak Inverse Voltage			PIV	85 (Min).	Volts
Average Rectified Current			lavg	200	mAmps
Continuous Forward Current			I <sub>Fdc</sub>	200	mAmps
Peak Surge Current (t <sub>peak</sub> = 1 sec.)			l <sub>peak</sub>	1.0	Amp
BKC Power Dissipation			P <sub>tot</sub>	500	mWatts
Operating Temperature Range			Τ <sub>ορ</sub>	-65 to +200	° C
Storage Temperature Range			T <sub>st</sub>	-65 to +200	° C
Electrical Characteristics @ 25 °C*	Symbol	Mi	nimum	Maximum	Unit
Forward Voltage Drop @ $I_F = 400 \text{ mA}$	$V_{F}$	*	***	1.10	Volts
Breakdown Voltage @ Ι <sub>R</sub> = 25 μA	PIV	8	85		Volts
Reverse Leakage Current @ V <sub>R</sub> = 50 V	l <sub>R</sub>			100	μΑ
Reverse Recovery time (note 1)	t <sub>rr</sub>			10	nSecs

Note 1: Per Method 4031-A with  $I_F = 10 \text{ mA}, Vr = 6 \text{ V}, R_L = 100 \text{ Ohms. * UNLESS OTHERWISE SPECIFIED}$ 



#### Silicon Switching Diode LL4608

LL-35 Glass Package

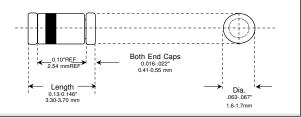
# **Applications**

Used in general purpose applications, where a controlled forward characteristic and fast switching speed are important.

# **Features**

- Six sigma quality
- Metallurgically bonded
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#### LL-34/35 MINI MELF Surface Mount Package DO-213AA



Maximum Ratings			Symbol	Value	Unit
Peak Inverse Voltage			PIV	85 (Min).	Volts
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